

In the claims:

Please amend the claims as follows:

1. (Currently Amended) A semiconductor device comprising:
a supporting substrate made of insulating material;
a conductive pattern provided on a surface of the supporting substrate;
an external connecting terminal provided on a back surface of the supporting substrate
and electrically connected to the conductive patterns;
a circuit element provided on the conductive pattern; and
a transparent glass plate that covers the circuit element and that forms a hollow airtight
portion between the supporting substrate and the transparent glass plate.
2. (Canceled)
3. (Original) A semiconductor device according to claim 1, wherein the supporting
substrate includes a flat supporting portion and a column portion, and the conductive patterns are
provided on the flat supporting portion.
4. (Currently Amended) A semiconductor device according to claim 1, wherein the
transparent glass plate is adhered onto the column portion.
5. (Original) A semiconductor device according to claim 1, wherein a via hole is provided
in the supporting substrate, and the circuit element and the external connecting terminals are
electrically connected through the via hole.
6. (Original) A semiconductor device according to claim 1, wherein the circuit element
is formed of one of a semiconductor element and a fuse element.
7. (Original) A semiconductor device according to claim 6, wherein the fuse element is
formed of a bonding wire.

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Claims 8 – 11 (Withdrawn)